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**IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE**

U.S. NON-PROVISIONAL PATENT APPLICATION

FOR

**METHOD OF MANUFACTURING ENHANCED THERMAL DISSIPATION
INTEGRATED CIRCUIT PACKAGE**

Inventors:
Edward G. Combs
Robert P. Sheppard
Tai Wai Pun
Hau Wan Ng
Chun Ho Fan
Neil R. McLellan

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06/18/2004 HVUONG1 00000016 10803782
01 FC:1201 -172.00 DP
02 FC:1202 -108.00 DP
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01 FC:1999 289.00 DP

Milbank, Tweed, Hadley & McCloy, LLP
One Chase Manhattan Plaza
New York, NY 10005

06/18/2004 HVUONG1 00000016 10803782
01 FC:1201 172.00 DP
02 FC:1202 108.00 DP
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